Product Specification :	Document No	PS-0801-01
Subject : SCT0801 Series Specification	Date Issued	2011/06/07
	Date Revised	2020//5/25
	Version	A

【INDEX】

Product Specification :	Document No	PS-0801-01
Subject : SCT0801 Series Specification	Date Issued	2011/06/07
	Date Revised	2020//5/25
	Version	A

【1. Scope】

This Specification Covers the 0.80mm Pitch SCT0801 Series Connector Specification.

【2.Spec and Part number】

Specification	Production No.	Picture of Product
Housing	SCT0801H-xxBBE110 SCT0801HA-xxFBE110	
Terminal	SCT0801TPS110	
Wafer	SCT0800WVS-xxF1BE501 SCT0800WRS-xxF1BK501 SCT0800WRS-xxF1BE501	

【3.Disposal of Material and surface】

Specification		Materials	Disposal of Surface
Terminal		Phosphor Bronze	Tin Plated: Over 70μ″ .Nickel: Over 30μ″ Gold Plated : Gold Flash″ ~3μ″ . Nickel : over 30μ″
Housing		LCP	UL 94V-0
Wafer	Base	LCP	UL 94V-0
	PIN	Phosphor Bronze	Tin Plated: Over 70μ″ .Nickel: Over 30μ″ Gold Plated : Gold Flash″ ~3μ″ . Nickel : over 30μ″
	Solder tab	Brass	Tin Plated: Over 70μ″ .Nickel: Over 30μ″ Gold Plated : Gold Flash″ ~3μ″ . Nickel : over 30μ″

Please Refer to the Project drawing for the above Specification)

【4. Ratings and applicable wires】

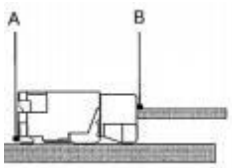
【Item】	【Standard】	
Rated Voltage (Max.)	30V	[AC/DC]
Rated Current (Max.)	0.5A	
Ambient temperature Range	-25℃~+105℃	
Applicable wire insulation O.D	AWG 32# Insulation O.D. 0.60mm(Max.)	

【Including terminal temperature rise.

Product Specification :	Document No	PS-0801-01
Subject : SCT0801 Series Specification	Date Issued	2011/06/07
	Date Revised	2020//5/25
	Version	A

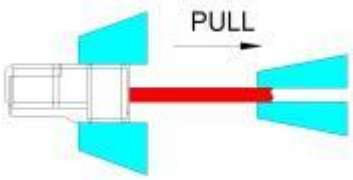
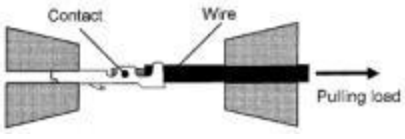
【5. PERFORMANCE】

5-1. Electrical Performance.

【Item】		【Test Condition】	【Requirement】
5-1-1	Contact Resistance	Mate connectors, measure by dry circuit, 20mV MAX, 10mA. (Based upon EIA-364-06A). 	Initial: 20 milliohms Max. After Test: 40 milliohms Max.
5-1-2	Insulation Resistance	Mate connectors, apply 250V DC between adjacent terminal or ground. (Based upon EIA-364-21B / MIL-STD-202 Method 302 Cond.B)	100 Megohms Min.
5-1-3	Dielectric Strength	Mate connectors, apply 200V AC for 1 minute between adjacent terminal or ground. (Based upon EIA-364-20A / MIL-STD-202 Method 301)	No Breakdown and Flashover
5-1-4	Contact resistance on crimped portion	Crimp the applicable wire on to the terminal measure by dry circuit 20mV MAX, 10mA.	20 milliohms Max.

Product Specification :	Document No	PS-0801-01
Subject : SCT0801 Series Specification	Date Issued	2011/06/07
	Date Revised	2020//5/25
	Version	A

5-2. Mechanical Performance.

【Item】		【Test Condition】	【Requirement】	
5-2-1	Insertion & withdraw Force	Insert and withdraw Connectors at the speed rate of 25.4±3mm/minute.	Refer to paragraph 6	
5-2-2	Terminal/ Housing Retention Force	Apply axial pull out force at the speed rate of 25.4±3mm/minute on the terminal assembled in the housing. 	3.43N {0.35kgf} Min.	
5-2-3	Terminal Insertion Force	Insert the crimped terminal into the housing.	4.9N {0.5kgf} Max.	
5-2-4	Pin Retention Force	Apply axial push force at the speed rate of 25.4±3mm/minute.	2.5N {0.25kgf} Min.	
5-2-5	Tensile strength (Crimped connections)	Fix the crimped terminal, apply axial pull out force on the wire. (Do not crimp insulation part). 	AWG# / Spec.kgf. Min. Note> As for unspecified wire sizes in this specification define values with clients	#32 / 0.3

Product Specification:	Document No	PS-0801-01
Subject : SCT0801 Series Specification	Date Issued	2011/06/07
	Date Revised	2020//5/25
	Version	A

5-3. Environmental Performance and Others.

【Item】		【Test Condition】	【Requirement】	
5-3-1	Repeated Insertion/ Withdrawal	When mated up to 30 cycles repeatedly by the rate of 10 cycles per minute.	Contact Resistance	40 milliohms Max.
5-3-2	Temperature Rise	Mating connectors shall be energized at rating current until thermal stability is achieved, and then measured the termperature rise. (EIA364-70,Method 1)	Temperature rise	30℃ Max.
5-3-3	Vibration test	Amplitude: 1.5mm P-P Sweep time: 10~55~10 HZ in 1 minute Duration: 2 hours in each X.Y.Z axials. (Based upon EIA-364-28B/MIL-STD-202 Method 213B Cond.A)	Appearance	No Damage
			Contact Resistance	40 milliohms Max.
			Discontinuity	1 micro-second Max.
5-3-4	Shock test	490m/s^2{50G}, 3 strokes in each X.Y.Z. axes. (Based upon EIA-364-27B/MIL-STD-202 Method 213B Cond.A)	Appearance	No Damage
			Contact Resistance	40 milliohms Max.
			Discontinuity	1 micro-second Max.
5-3-5	Heat Resistance	105±2℃,96 hours. (Based upon MIL-STD-202 Method 108A Cond.A)	Appearance	No Damage
			Contact Resistance	40 milliohms Max.
5-3-6	Cold Resistance	-40±5℃,96 hours.	Appearance	No Damage

Product Specification:	Document No	PS-0801-01
Subject: SCT0801 Series Specification	Date Issued	2011/06/07
	Date Revised	2020//5/25
	Version	A

	Cold Resistance	(Based upon EIA-364-105)	Contact Resistance	40 milliohms Max.
【Item】		**【Test Condition】**	**【Requirement】**	
5-3-7	Humidity	Temperature: 40±2C Relative Humidity: 90~95% Duration: 96 hours (Based upon EIA-364-31A/MIL-STD-202 Method 103B Cond.B)	Appearance	No Damage
			Contact Resistance	40 milliohms Max.
			Dielectric Strength	Must meet 5-1-3
			Insulation Resistance	40 Megohms Min.
5-3-8	Temperature Cycling	5 cycles of: a) -40C 30 minutes. b) +105C 30 minutes. (Based upon EIA-364-32B)	Appearance	No Damage
			Contact Resistance	40 milliohms Max.
5-3-9	Salt Spray	24±1 hours exposure to a salt spray from the 5±1% solution at 35±2C . (Based upon EIA-364-26B/MIL-STD-202 Method 101D Cond.B).	Appearance	No Damage
			Contact Resistance	40 milliohms Max.
5-3-10	Solder-ability	Soldering Time: 3~5second. Solder Temperature: 255±5C . (Based upon EIA-364-52)	Solder Wetting	95% of immersed area must show no voids, pin holes.
5-3-11	Solder-Resistance	Soldering time:5~10 sec solder. Temperature:245+5/-5C . (Based upon EIA-364-56A)	Appearance	No Damage

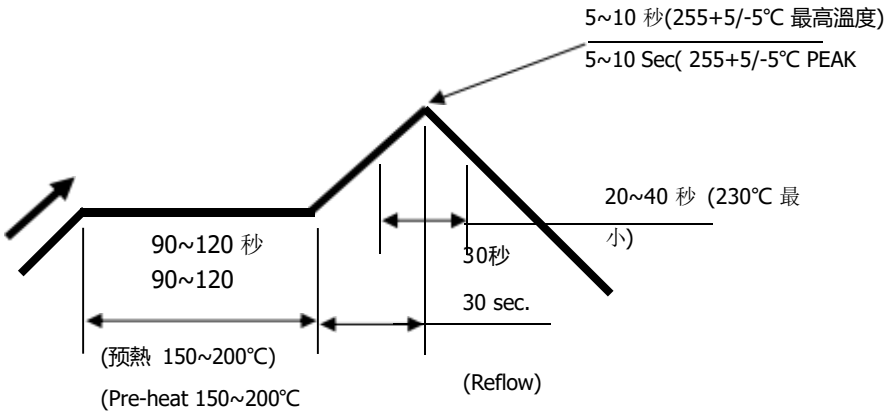
【6. INSERTION/WITHDRAWAL FORCE】<Connector mating force>

Product Specification:	Document No	PS-0801-01
Subject: SCT0801 Series Specification	Date Issued	2011/06/07
	Date Revised	2020//5/25
	Version	A

No. of CKT	First Insertion (kgf Max.)	30th Withdrawal (kgf Min.)	No. of CKT	First Insertion (kgf Max.)	30th Withdrawal (kgf Min.)
02	1.20	0.08	13	2.30	0.52
03	1.30	0.12	14	2.40	0.56
04	1.40	0.16	15	2.50	0.60
05	1.50	0.20	16	2.60	0.64
06	1.60	0.24	17	2.70	0.68
07	1.70	0.28	18	2.80	0.72
08	1.80	0.32	19	2.90	0.76
09	1.90	0.36	20	3.00	0.80
10	2.00	0.40	21	3.10	0.84
11	2.10	0.44	22	3.20	0.88
12	2.20	0.48			

Note ： Insertion and Withdrawal for 30Cycles

【7.SMT REFLOW CONDITION】



TEMPERATURE CONDITION GRAPH/ (TEMPERATURE ON BOARD PATTERN SIDE)

Notes: Please check the reflow soldering condition by your own devices beforehand. Because the condition changes by the soldering devices, P.C. boards, and so on.